Impactron-A New Solid State Image Intensifier

By: Jaroslav Hynecek
ISETEX, INC.
608 Tiffany Trail Richardson, TX 75081
hynecek@swbell.net

Abstract

This article describes the theory of operation and up to date achieved performance of a new image sensor concept that is using Impact Ionization to multiply photo-generated charge before sensing. It is shown that the charge multiplication based on a single carrier Impact Ionization is almost noiseless. This allows detected signal charge to be amplified directly in the charge domain and be always kept above the charge detector amplifier noise floor. Charge is repeatedly transferred in a CCD fashion through high field regions where the impact ionization occurs. Even though the impact ionization has a low probability and the high field regions are short the number of transfers is large and the significant charge gains are obtained. The developed charge multiplication structure can be easily incorporated into pixels of any standard CCD image sensor and included in the image sensing area, the memory area, or any other vertical or horizontal CCD register with a minimum area penalty. The article describes in detail the theory of charge multiplication and excess noise generation. The developed theory is supported by the measured data obtained form the test image sensors. The measurement methods used to characterize the charge multiplication gain and noise are also described in detail.

I. Introduction

The charge domain multiplication using Impact Ionization has been proposed previously to improve sensitivity and noise of existing CCD image sensors [1, 2, 3, 4]. Since it seems difficult to reduce the noise floor of existing charge detection amplifiers to a single electron, particularly at high clocking frequencies, it is beneficial to focus attention on multiplying photo-generated charge directly in the charge domain before its conversion into a voltage. The charge multiplication is achieved by creating a high-field region between two neighboring gates of a standard CCD structure and charge is injected into this field. When electrons traverse the high-field region they gain energy and when certain threshold is exceeded cause Impact Ionization. It is well known that the threshold for impact ionization is sharp and depends on the crystallographic orientation [5]. The electrons involved in ionizing collisions have to satisfy both the momentum and the energy conservation rules and this leads to a very narrow variance of Impact Ionization process. The small variance is important for noise, since many consecutive CCD charge transfers are required to achieve reasonable charge multiplication gains. In the following sections it will be shown that a reasonable window of operation for achieving the well controlled multiplication gain and at the same time low noise can be found.

II. The Theory of Impactron Operation

A cross section along the charge transfer channel of a typical CCD register that includes the Charge Carrier Multiplier (CCM) structure is shown in Fig. 1. The process used for the device fabrication was the standard Virtual Phase (VPCCD) process [6] where the single polysilicon gate was split into several sections as is shown in the figure. When the gate ϕ_1 is gradually biased to its high clocking level electrons begin to transfer from the Virtual Phase region into the high field region that was created previously by the high gate bias applied to ϕ_{cm}. During this process some electrons undergo impact ionization and new electron hole pairs are created. The new electrons are collected in potential wells where they are added to the original signal. The holes escape either to the substrate or to channel stops and do nor participate in the multiplication process any further. By lowering bias on the gates in a suitable order charge can be transferred either to the next VP region or back to the original well from where it has originated. If the CCM structure is located in the image sensing area the charge multiplication process can be performed, for example, at the end of the integration period just before the transfer into the memory or vertical registers. In the case of CCM located in the serial register, charge can be multiplied as it progresses in one direction toward the readout amplifier.

The charge multiplication gain depends on the high-level bias of the charge multiplication gate ϕ_{cm} and on the number of transfer pulses. Both of these can be easily varied when the CCM is incorporated in the sensor image area. When the CCM is located in the serial register the number of transfers is determined by the register design and only the clock amplitude controls the gain.

However, the most important parameter of the charge multiplication process is its noise. It is customary to characterize noise in Image Intensifiers by introducing the excess noise factor "F" [7] as follows:

$$F^2 = (1/M^2)\cdot(\sigma_m^2/\sigma_i^2)\,, \tag{1}$$

where σ_m is the standard deviation of multiplied number of electrons, σ_i is the standard deviation of injected number of electrons, and M is the average multiplication gain. Since the multiplication process in CCD consists of many individual steps, it is necessary to understand how the number of steps affects noise.

When two random processes A, and B are cascaded, the standard deviation of the resulting process follows the formula [7]:

$$\sigma_{AB}^2 = n_B^2\sigma_A^2 + n_A\sigma_B^2\,, \tag{2}$$

where n_A and n_B are the average numbers of carriers entering each process. By repeatedly applying Equation (2) N times, where N is the number of CCD transfers, and combining the result with Equation (1) it is possible to express the excess noise factor F in terms of the multiplication gain n_o and the standard deviation σ_o of a single multiplication step:

$$F^2 = 1+\sigma_o^2(1-1/M)/(n_o^2-n_o)\,, \tag{3}$$

where $M = n_o^N$. Since it is expected that the multiplication gain of a single step is very close to unity, the formula can be further simplified and approximated as follows:

$$F^2 \approx 1+\sigma_o^2 N(1-1/M)/\ln(M)\,. \tag{4}$$

This result is suitable for comparison with experiments, since it depends only on one unknown parameter σ_o. By measuring excess noise as function of the number of multiplication steps N it is possible to determine the value of σ_o. To find the theoretical value for σ_o will be left for future work since this requires overcoming many computational obstacles that are beyond the scope of this article. An estimate can be obtained by considering that the impact ionization threshold is not sharp due to phonon interactions. Comparing the corresponding energies leads to:

$$\sigma_o \approx E_p/E_t\,. \tag{5}$$

Using the minimum impact ionization threshold for silicon E_t = 1.18eV [5], and the dominant phonon energy E_p = 51mV[9], the result is σ_o = 0.043. This estimate therefore suggests that a relatively large number of transfers can be used before excess noise grows much larger than unity. The small size of σ_o is an advantage for the single carrier impact ionization process used in this device. The electrons always start from the same initial condition before the impact ionization occurs. This can be contrasted with the avalanche multiplication processes where the multiplied electrons continue to be accelerated and continue to ionize. This leads to a larger excess noise factor as can be seen for example in the recently published work on CMOS image sensor using avalanche photodiode pixels [8].

To predict the dependency of multiplication gain on gate bias the formula derived by Okuto and Crowell [9] for the carrier multiplication coefficient α, can be used:

$$\alpha(F) = (eF/E_t)\cdot\exp(a-\sqrt{a^2+x^2})\,, \tag{6}$$

where: $a = 0.217\cdot(E_t/\hbar\omega_o)^{1.14}$, $x = E_t/(eFL)$, e is the electron charge, F is the electrical field, $\hbar\omega_o$ is the dominant phonon energy, and L is the carrier mean free path. Since the field between the gates is not very uniform Equation (6) would have to be integrated over the carrier traveling distance. However, this would unduly complicate the calculations. To simplify the problem it is assumed that a constant effective field F_{eff} is acting over an effective carrier traveling distance $L_{eff.}$ The field intensity in silicon is also reduced by the presence of the gate oxide and by the finite depth of the depletion region. It will thus be further assumed that: $F_{eff} = \beta\cdot(V_{cm}-V_g)/L_{eff}$ where the V_{cm} is the multiplication gate high bias level, V_g is the register gate bias at which the carriers begin their injection into the high field region, and β is the bias reduction factor in Volts. Finally, it will be assumed that the field is relatively week leading to $x >> a$. This approximation is some times called the Shockley's "lucky electron" model [5]. With these assumptions and simplifications Equation (6) can be recast in the form suitable for a comparison with experiments as follows:

$$\ln((M^{\frac{1}{N}}-1)/(V_{cm}-V_g)) = A_o - B_o/(V_{cm}-V_g)\,, \tag{7}$$

where: $M = (1+\alpha\cdot L_{eff})^N$, $A_o = a+\ln(e\beta/E_t)$, and $B_o = (L_{eff}/L)\cdot E_t/(e\beta)\cdot$

III. Gain and Noise Measurements

The multiplication gain of the Impactron is easily measured. It was found that the most straightforward way is to vary the light intensity and measure the output with the CCM turned on and off respectively. At the same time excess noise is also evaluated. Selecting an average pixel of the array and statistically evaluating its output for many frames accomplishes this task. Both the mean and variance are found and used to calculate the excess noise factor F. Assuming that the input photon flux obeys the Poisson statistics and that the system conversion gain "A" that relates the number of detected electrons to the measured voltage v_m is known, Equation (1) can be transformed as follows:

$$F^2 = (\langle v_m^2\rangle - \langle v_m\rangle^2)/(\langle v_m\rangle A\cdot M)\,. \tag{8}$$

The result for the multiplication gain M plotted as function of the high clocking bias V_{cm} for N = 400 is shown in the graph in Fig. 2a. From the graph it can be seen that the multiplication gain up to 120 has been achieved with a modest clock high biasing level.

Fig. 2b shows the plots of the multiplication gain versus $1/(V_{cm}–V_g)$ for V_g =3V according to Equation (7) and also for several different temperatures. The data show a good agreement with the predicted linear dependency. The multiplication gain depends on temperature and is larger for lower temperatures largely due to the mean free path temperature dependency. This can be also derived from Equation (6) [9]. The plots in Fig. 2b allow extraction of the carrier mean free path from the constant B_o. From the graphs we have $B_o \cong 120$. Assuming that $\beta = 0.8$ and $L_{eff} \cong 0.5$ um, for the particular device used, the mean free path is: L = 61 Angstroms. This is a reasonable value.

The excess noise factor F^2 is plotted for M = 14 as function of N in a graph shown in Fig 2c. From this graph it can be observed that excess noise depends on N linearly as predicted by Equation (4). From the data it is also possible to extract the value of σ_o, which is $\sigma_o = 0.04$. This compares well with the number presented in the previous section considering that only a simple estimation was used.

IV. Discussion of test results

From the graph in Fig. 2c it is concluded that a reasonable number of transfers that will keep the excess noise factor below $F^2 = 1.3$ is approximately 400. The CCM gain that was used with this number of transfer was approximately 14. However, the gain can be easily increased to more than 50 and for this case the Single Photon Detection (SPD) is possible. The multiplication gain of devices with the multiplier in the image area pixels, however, is limited by the well capacity of the pixels. The multiplication is also different for each pixel, which produces a large fixed pattern noise. This needs to be corrected by a complicated off chip signal processing system if such devices are to be used for high quality imaging. For this reason another device (Texas Instruments TC253 [10]) with the multiplier in serial register was designed and tested. The photographs of the test target with the CCM gain turned off and with the CCM gain equal to M = 32 are shown in Figs. 3a and 3b respectively. The picture with the CCM gain turned on was obtained by inserting a Neutral Density filter with 32x attenuation in front of the lens and keeping the illumination intensity unchanged. The dark current limited the noise floor of this device. To achieve the SPD operation a moderate cooling or shorter integration times are required.

V. Conclusions

A novel high sensitivity solid-state image sensor concept has been developed and tested. The concept includes charge multiplication function in its operation that is similar to one used in the vacuum tube Image Intensifiers. The charge multiplication is performed in the charge domain before charge is converted into a voltage. This obviates problems associated with the present day image sensor high charge detection amplifier noise floors. The charge multiplication is based on a single carrier Impact Ionization process that occurs when carriers are transported through the regions with high electric field. It is shown theoretically and confirmed by measurements that the single carrier Impact Ionization is a low noise process that permits development of image sensors with a superb, single photon, low light level sensitivity. The charge multiplication process was modeled by the impact ionization formula derived by Okuto and Crowell and a good agreement with the measurement was obtained.

Acknowledgments

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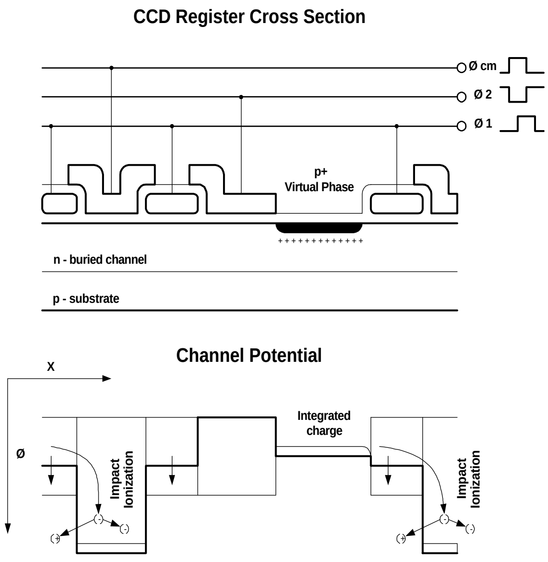

Fig. 1. Cross-section of a typical CCD register containing the CCM structure that was fabricated using the Split-Gate Virtual-Phase technology.

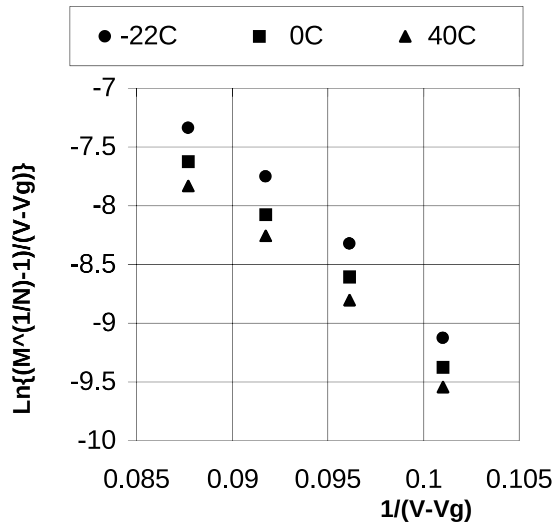

Fig. 2b. Graphs of the Charge Multiplication Factor as Function of 1/(Vcm-Vg) according to Equation (7) for different temperatures. Vg used in Equation (7) was 3V.

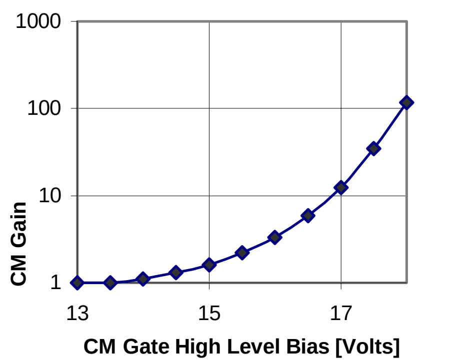

Fig. 2a. Graph of the Charge Multiplication Gain as function of the multiplication gate high clock bias.

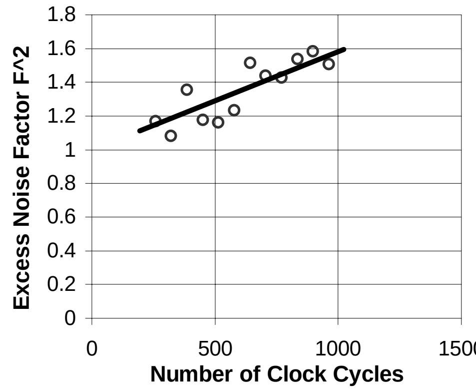

Fig. 2c. Graph of the Excess Noise Factor as Function of the number of CCD transfers for multiplication gain of 14.

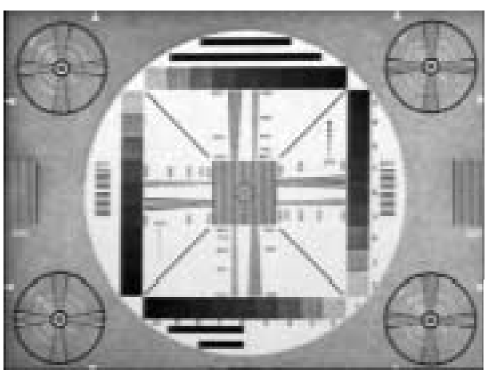

Fig. 3a. Photograph of the test target imaged by CCD image sensor TC253 with CCM turned off.

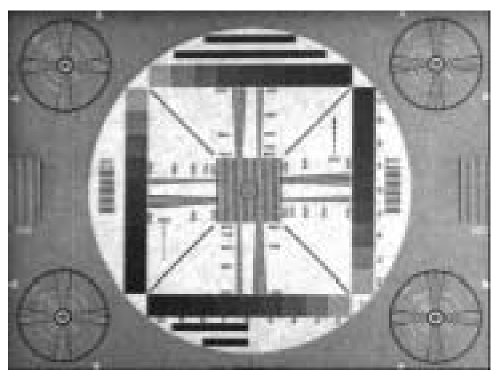

Fig. 3b. Photograph of the same target imaged by the same CCD with the CCM on and with the ND filter attenuating by 32x inserted in front of the lens.